

Title (en)
INDIUM ELECTROPLATING BATHS FOR THIN LAYER DEPOSITION

Title (de)
INDIUM-ELEKTROPLATTIERUNGSBÄDER ZUR DÜNNSCHICHTABSCHEIDUNG

Title (fr)
BAINS D'ÉLECTRODÉPOSITION À L'INDIUM POUR DÉPÔT DE COUCHE MINCE

Publication
EP 2245216 A1 20101103 (EN)

Application
EP 09706296 A 20090128

Priority

- US 2009032291 W 20090128
- US 2211308 A 20080129

Abstract (en)
[origin: US2009188808A1] Indium (In) electroplating solutions which are used to deposit compositionally pure, uniform, substantially defect free and smooth In films with near 100% plating efficiency and repeatability. In one embodiment the plating solution includes an In source, citric acid and its conjugate pair salt and a solvent. At a pH value of below 4.0, sub-micron thick In layers with close to 100% purity at close to 100% plating efficiency are produced. Such In layers are used in fabrication of electronic devices such as thin film solar cells.

IPC 8 full level
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CPC (source: EP US)
C25D 3/54 (2013.01 - EP US); **H01L 31/0322** (2013.01 - EP US); **H01L 31/0749** (2013.01 - EP US); **Y02E 10/541** (2013.01 - EP US); **Y02P 70/50** (2015.11 - EP US)

Cited by
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AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO SE SI SK TR

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US 2211308 A 20080129; EP 09706296 A 20090128; TW 98103278 A 20090202; US 2009032291 W 20090128